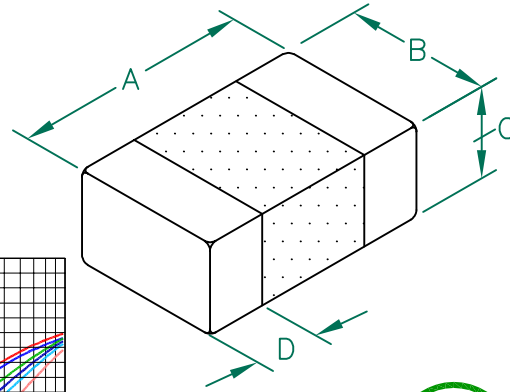


MI0805K110R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

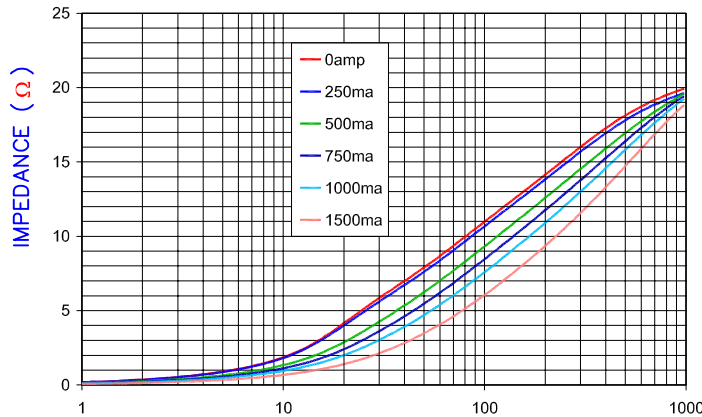
A	2.00 [.079]	+ 0.20 [.008]
B	1.25 [.049]	+ 0.20 [.008]
C	0.90 [.035]	+ 0.20 [.008]
D	0.51 [.020]	+ 0.25 [.010]



ELECTRICAL CHARACTERISTICS:

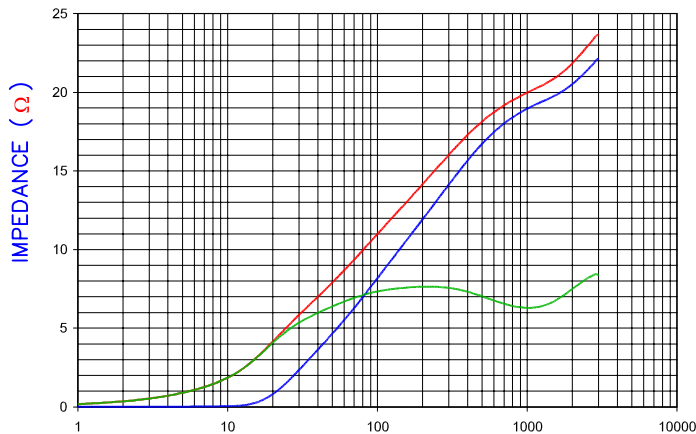
Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	11	
Minimum	8	
Maximum	14	0.06
		1500 mA

Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)

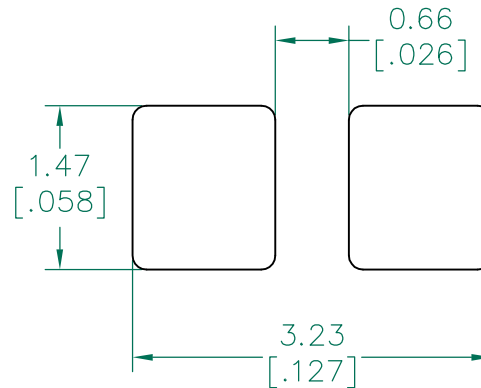
|Z|, R, AND X vs. FREQUENCY



FREQUENCY (MHz)

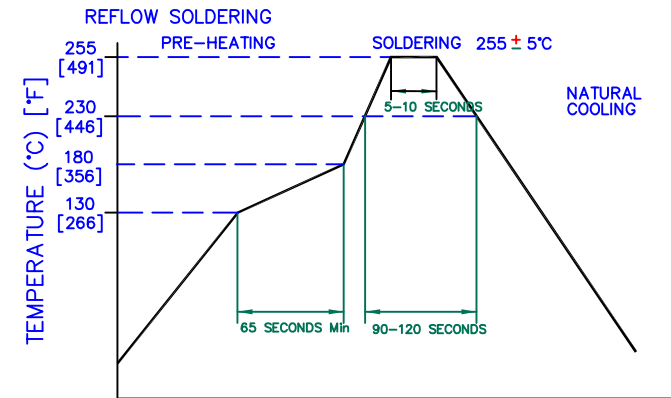
— Z — R — X_L

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 [.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].

This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.



REV	DESCRIPTION	DATE	INT	PROJECT/PART NUMBER:	REV	PART TYPE:	DRAWN BY:
E	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	MI0805K110R-10	E	CO-FIRE	TMB
D	CHANGE TO PAPER TAPE	03/04/10	JUN				
C	UPDATE COMPANY LOGO	08/06/08	JRK				
B	ADD ROHS & UPDATE COMPANY LOGO	08/28/07	JRK				
A	ORIGINAL DRAFT	04/05/04	TMB				
REV	DESCRIPTION	DATE	INT	DATE: 04/05/04	SCALE: -	SHEET: 2 of 2	

